EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(suga near3 hirofumi).in. and semiconductor near3 laser and heat near3 sink	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 15:33
L2	19	(kan near3 hirofumi).in. and semiconductor near3 laser and heat near3 sink	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 15:33
L3	11	(miyajima near3 hirofumi).in. and semiconductor near3 laser and heat near3 sink	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 15:43
L4	5	(nobuo near3 watanabe).in. and semiconductor near3 laser and heat near3 sink	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 15:45
L5	69	372/35.ccls. and (resin or epoxy)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 15:46
L7	250	372/36.ccls. and (resin or epoxy) and semiconductor near3 laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 15:57
L8	110	372/34.ccls. and (resin or epoxy) and semiconductor near3 laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 15:58
L9	198	7 not 8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 15:58

L10	73	372/43.01.ccls. and (resin or epoxy) and heat near3 sink$1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 16:03
L11	187	semiconductor near3 laser and (resin or epoxy) and heat near3 sink$1 and ((cool$3 near3 (fluid or water)) or coolant)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 16:06
L12	183	11 not 10	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 16:06
L13	169	12 not 8	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 16:07
L14	153	13 not 7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 16:07
L15	1731	372/34.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 16:40
L16	601	372/35.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 17:13
L17	1306	372/36.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/23 17:27
L18	1	(semiconductor near3 laser and (resin or epoxy) and heat near3 sink$1 and ((cool$3 near3 (fluid or water)) or coolant)).clm.	US-PGPUB	OR	ON	2008/09/23 17:54

L19	0	"10577958"	US-PGPUB; USPAT	OR	OFF	2008/09/23 17:56
S2	22	372/35.ccls. and (resin or epoxy) and semiconductor near3 laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/22 11:55
S3	109	372/34.ccls. and (resin or epoxy) and semiconductor near3 laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/22 11:58
S4	249	372/36.ccls. and (resin or epoxy) and semiconductor near3 laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/22 12:00
S5	2	(("6233944") or ("4368776")).PN.	US-PGPUB; USPAT	OR	OFF	2008/09/22 13:03
S6	0	(miyajima near3 hirobumi).in.	US-PGPUB; USPAT	OR	ON	2008/09/22 13:04
S7	0	(suga near3 hirobumi).in.	US-PGPUB; USPAT	OR	ON	2008/09/22 13:04
S8	220	(suga near3 hirobumi).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/22 13:04
S9	73	(suga near3 hirobumi).in. and semiconductor near3 laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/22 13:05
S10	16	(suga near3 hirobumi).in. and semiconductor near3 laser and heat near3 sink	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/09/22 13:05

9/23/08 6:00:04 PM
C:\Documents and Settings\arodriguez\My Documents\EAST\Workspaces\10577958.wsp